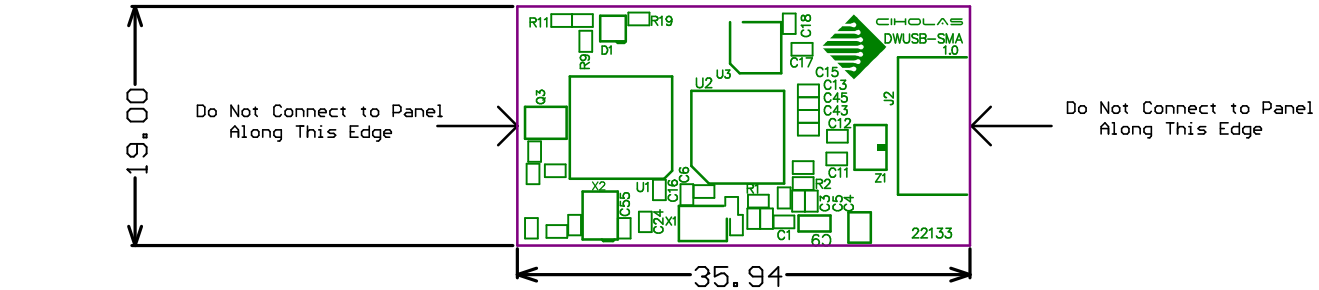


Layer	Name	Material
1	Top Paste	
2	Top Overlay	
3	Top Solder	Solder Resist
4	Component Side	Copper
5	Dielectric1	FR-4
6	Ground Plane	Copper
7	Dielectric2	FR-4
8	Power Plane	Copper
9	Dielectric3	FR-4
10	Solder Side	Copper
11	Bottom Solder	Solder Resist
12	Bottom Overlay	
13	Bottom Paste	

1.6mm +- 10% finished board thickness  
CONTROLLED IMPEDANCE

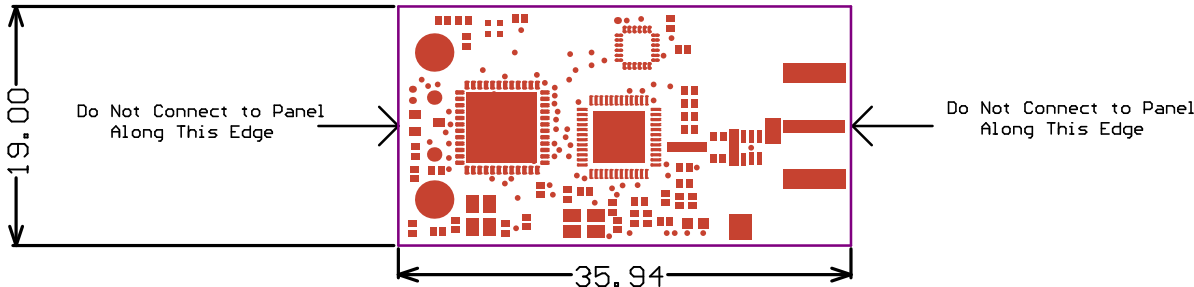
50 ohm +-10% single-ended impedance, top layer; 0.95mm wide  
Maintain 1mm separation to top layer ground pour on 50 Ohm traces.  
100 ohm +-10% differential impedance, top layer; 0.235mm wide 0.127 mm spacing

1 Oz. Finished Copper  
ENIG or silver immersion pad finish  
White Legend Top and Bottom  
Red Solder Mask Top and Bottom  
Fabricate board in a 2 by 5 array  
with 6.5mm minimum border and 3.5mm tooling holes.  
PCB edge remnant from panelization should  
be removed after assembly  
ROHS Compliant FR-4



Title : DWUSB-SMA Engineer : Dirk Van Vorst  
Part Number : DWUSB-SMA-UNPOP vanvorst@ciholas.com  
Revision : 1.0.2 (812)962-9410  
SVN : 22133  
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CONTROLLED IMPEDANCE

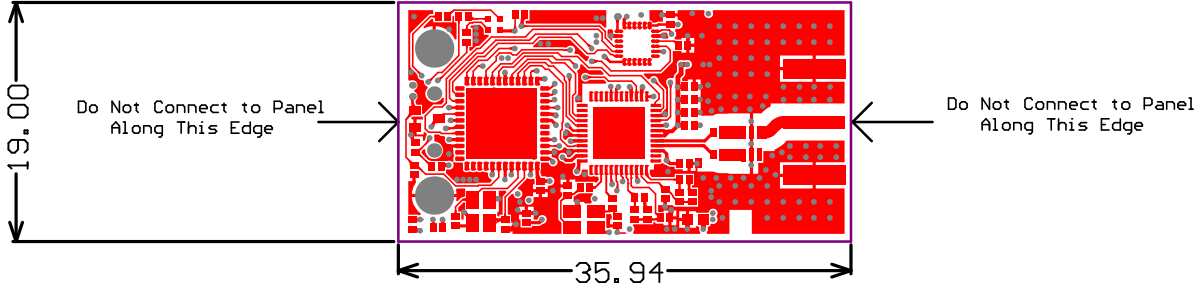
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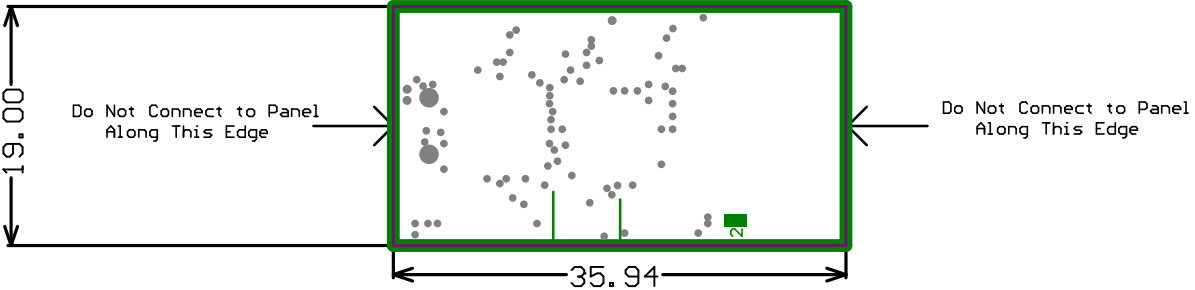
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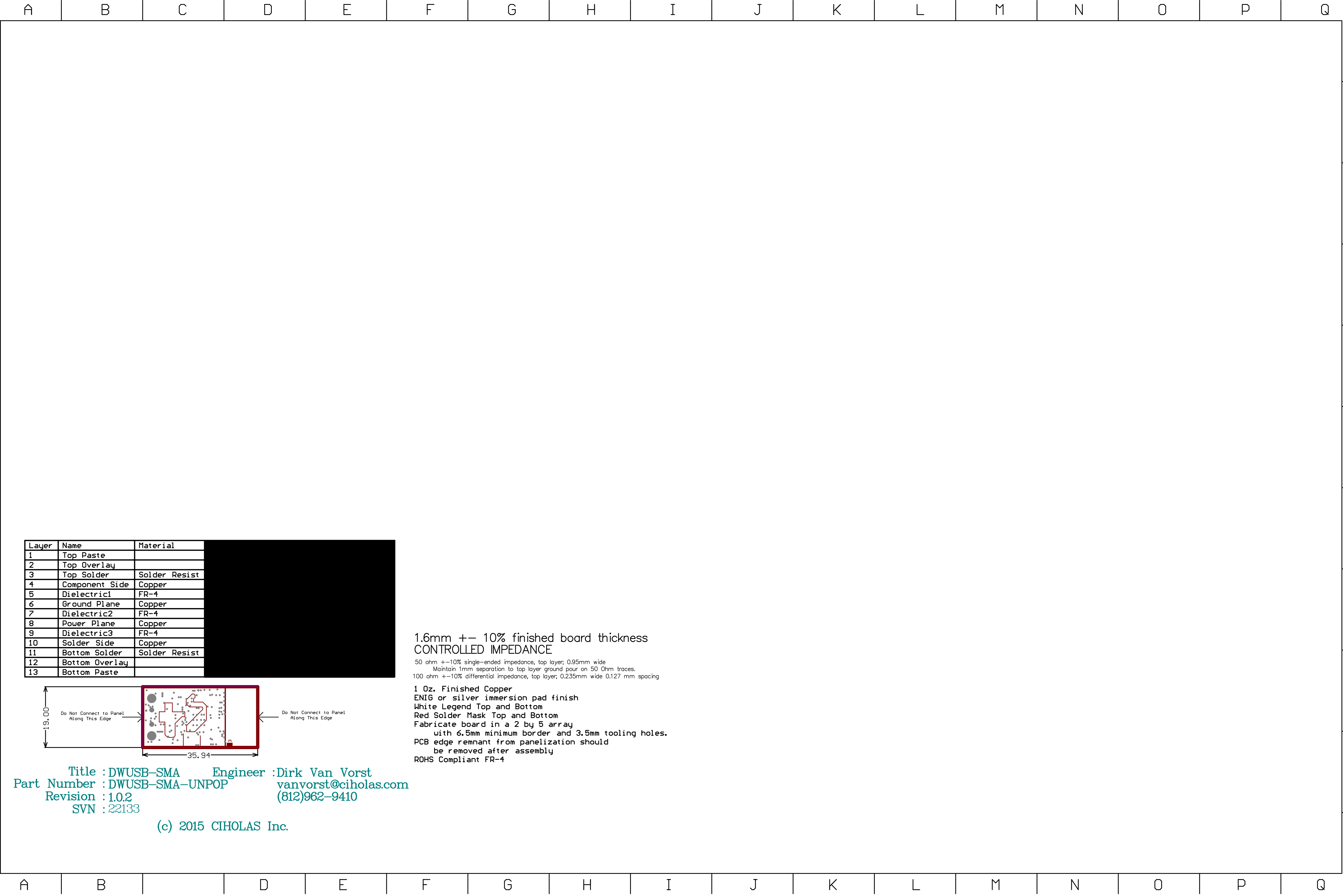
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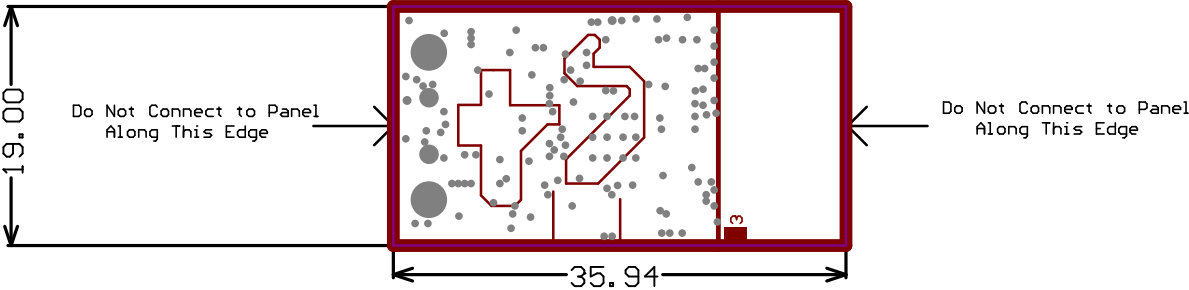


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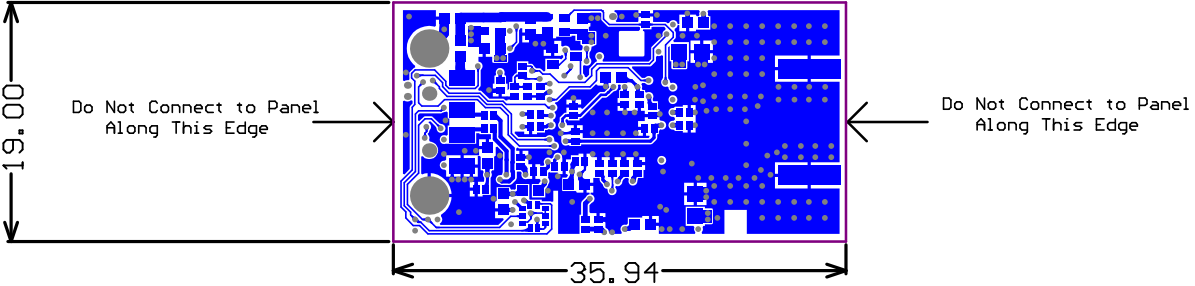
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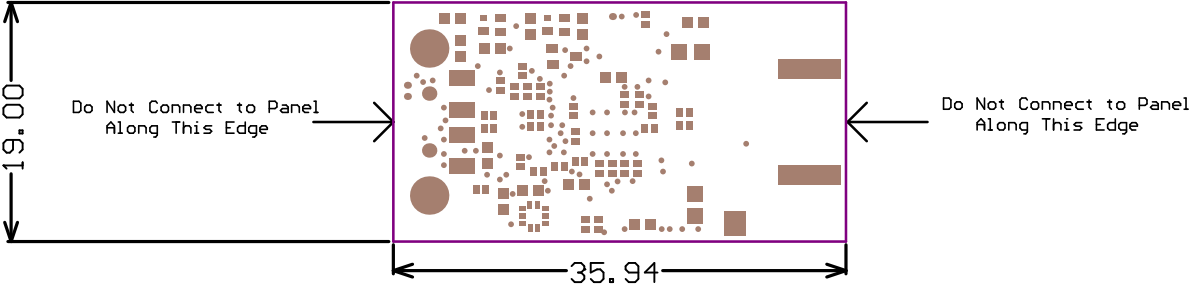


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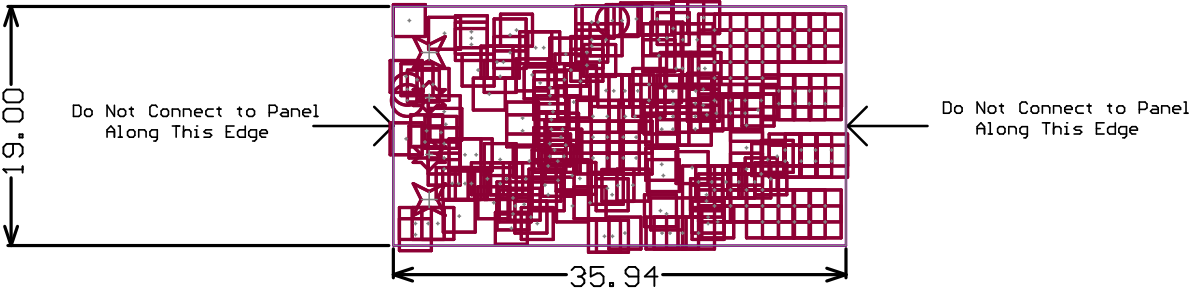
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Symbol	Hit Count	Finished Hole Size	Plated	Hole Type
✱	2	45.00mil (1.143mm)	NPTH	Round
✕	2	98.43mil (2.500mm)	PTH	Round
○	3	12.00mil (0.305mm)	PTH	Round
□	237	8.00mil (0.203mm)	PTH	Round
	244 Total			

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